

Product / Process Change Notice

PCN No.: Q000-PCN-PA202011-01

Date: 2020-11-24.

| | | | |
|--|--|---------------------------------|------------------------|
| <p>Change Title: <u>Add Greatek assembly and testing site at Tou-Fen factory</u></p> <p>Change Classification: <input checked="" type="checkbox"/> Major <input type="checkbox"/> Minor</p> <p>Change item: <input type="checkbox"/> Design <input type="checkbox"/> Raw Material <input type="checkbox"/> Wafer FAB <input checked="" type="checkbox"/> Package Assembly <input checked="" type="checkbox"/> Testing <input type="checkbox"/> Others: _____</p> | | | |
| <p>Affected Product(s) :</p> <p>The affected part no. list, please refer to the Table 1 for more information.</p> | | | |
| <p>Description of Change(s) :</p> <p>Nuvoton's assembly and testing subcontractor, GREATEK Technology Inc., adds one new factory to expand manufacture capacity of assembly and testing. The new factory is qualified site by Nuvoton for assembly and testing process.</p> <p><u>New site</u></p> <p>Toufen factory (No.9 , ZhuongMin Road ,Toufen, Miaoli, Taiwan(R.O.C.)).</p> | | | |
| <p>Reason for Change(s) :</p> <p>To increase manufacturing capacity and flexibility and to have multiple manufacturing routes.</p> | | | |
| <p>Impact of Change(s) : (positive & negative)</p> <p>Form: No change.</p> <p>Fit: No change.</p> <p>Function: No change.</p> <p>Reliability: No concern. (Passed qualification.)</p> | | | |
| <p>Qualification Plan/ Results :</p> <p>Passed the qualification of assembly packages and testing machines correlation, please refer to appendix A~B for the detailed report.</p> | | | |
| <p>Implementation Plan :</p> <p>1. This PCN is the formal announcement of the site change in process.</p> <p>2. Nuvoton is ready to execute this PCN immediately after customer approval. Therefore, if customer approval is obtained prior to the implementation date, Nuvoton will make this PCN effective right afterwards.</p> <p><input type="checkbox"/> Date Code: _____ onward <input type="checkbox"/> Lot No.: _____ onward <input type="checkbox"/> Implemented date: <u>Feb. 22, 2021 (scheduled)</u></p> | | | |
| Originator: | H.Y. Lai / Q100 | Approval:(QRA Director) | C.H. Shen/ Q000 |
| Contact for Questions & Concerns | <p>Name: <u>HYLai</u> TEL: <u>886-3-5770066 (ext. 31226)</u> FAX: <u>886-3-5792673.</u></p> <p>Address: <u>No.4, Creation Rd. III Science-Based Industrial Park Hsinchu, Taiwan, R.O.C..</u></p> <p>E-mail: <u>hylai0@nuvoton.com.</u></p> | | |

Customer Comments:

Note: Please sign this notice, and return to **Nuvoton** contact window within **30** days. If no response is received within **30** days, this Change Request will be assumed to meet your approval.

| | | |
|-----------------------------------|--------------------------------------|---|
| <input type="checkbox"/> Approval | <input type="checkbox"/> Disapproval | <input type="checkbox"/> Conditional Approval: _____. |
| Date: _____ | Dept. name: _____ | Person in charge: _____. |

Follow-up and Tracing:

A. copies to

FAB : Integration _____ _____ _____ _____ _____.

Test / Product: _____ _____ _____ _____ _____.

Design/ Marketing: _____ _____ _____ _____ _____.

Production control/ Others: _____ _____ _____ _____ _____.

B. Changes:

1. Document / Test program:

| Document No/ test program | Document name/ test program name | version | | responsibor | Completed date | Remark |
|---------------------------|----------------------------------|---------|-------|-------------|----------------|--------|
| | | before | after | | | |
| NA | NA | NA | NA | NA | NA | NA |

Verified by: _____.

Table 1: Affected part lists

| Part No. | Part No. | Part No. | Part No. | Part No. |
|--------------|------------|--------------|-------------|-------------|
| AIQIM101 | M0516ZDE | MINI54TDE | NAU8225YG | NCT7802Y |
| BT001 | M058ZDN | MINI54ZDE | NAU8315YG | NM1120XC1AE |
| DST-V001 | M2351ZIAAE | MINI57TDE | NAU85L40YG | NM1200TBAE |
| DTS2351ZIAAE | M251ZD2AE | MINI58TDE | NAU85L40YGB | NM1200ZBAE |
| ETQ7620 | M252ZC2AE | MINI58ZDE | NAU8810YG | NM18101Y |
| HL004 | M252ZD2AE | ML51TB9AE | NAU8814YG | NM18107Y |
| HL008 | M263ZIAAE | ML51TC0AE | NAU88C22YG | NUC029TAE |
| I2115AYYI | M481ZGAAE | ML51XB9AE | NAU88L21YG | NUC029TAN |
| I2115AYYIR | M481ZGCAE | MS51TC0AE | NCT3532Y | NUC029ZAN |
| I2130YYI | M481ZIDAE | MS51XB9AE | NCT3532Y-L | NUC029ZPOE |
| I2130YYIR | M482ZGCAE | MS51XC0BE | NCT3953Y-D | NUC102ZD2AN |
| LC002 | M482ZIDAE | N76E003AQ20 | NCT5510Y-D | NUC121ZC2AE |
| LC002A | M485ZIDAE | NANO102ZB1AN | NCT5532Y-B | NUC122ZD2AN |
| M030TD2AE | MI48 | NANO102ZC2AN | NCT5605Y | NUC122ZD2DN |
| M031TB0AE | MINI51TDE | NANO103ZD3AE | NCT5635Y | NUC125ZC2AE |
| M031TC1AE | MINI51ZDE | NANO112LB1AN | NCT5655Y | TZ0801 |
| M031TD2AE | MINI52TBN | NAU82011YG | NCT5946Y | XFC40QA |
| M032TD2AE | MINI52ZDE | NAU8224YG | NCT7362Y | YM0232A-04T |

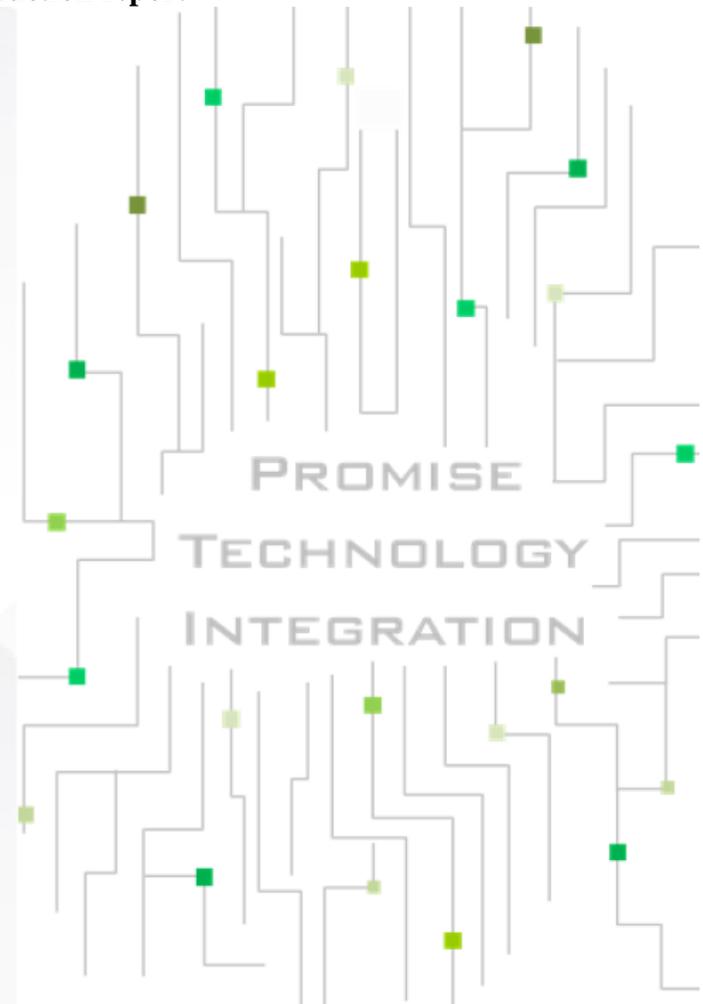
Appendix A: Greatek management introduction report



超豐電子股份有限公司
GREATEK ELECTRONICS INC.

Greatek Management Introduction

Purpose :
Product Management & Engineering of Site3 unify with Site1/2



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Content

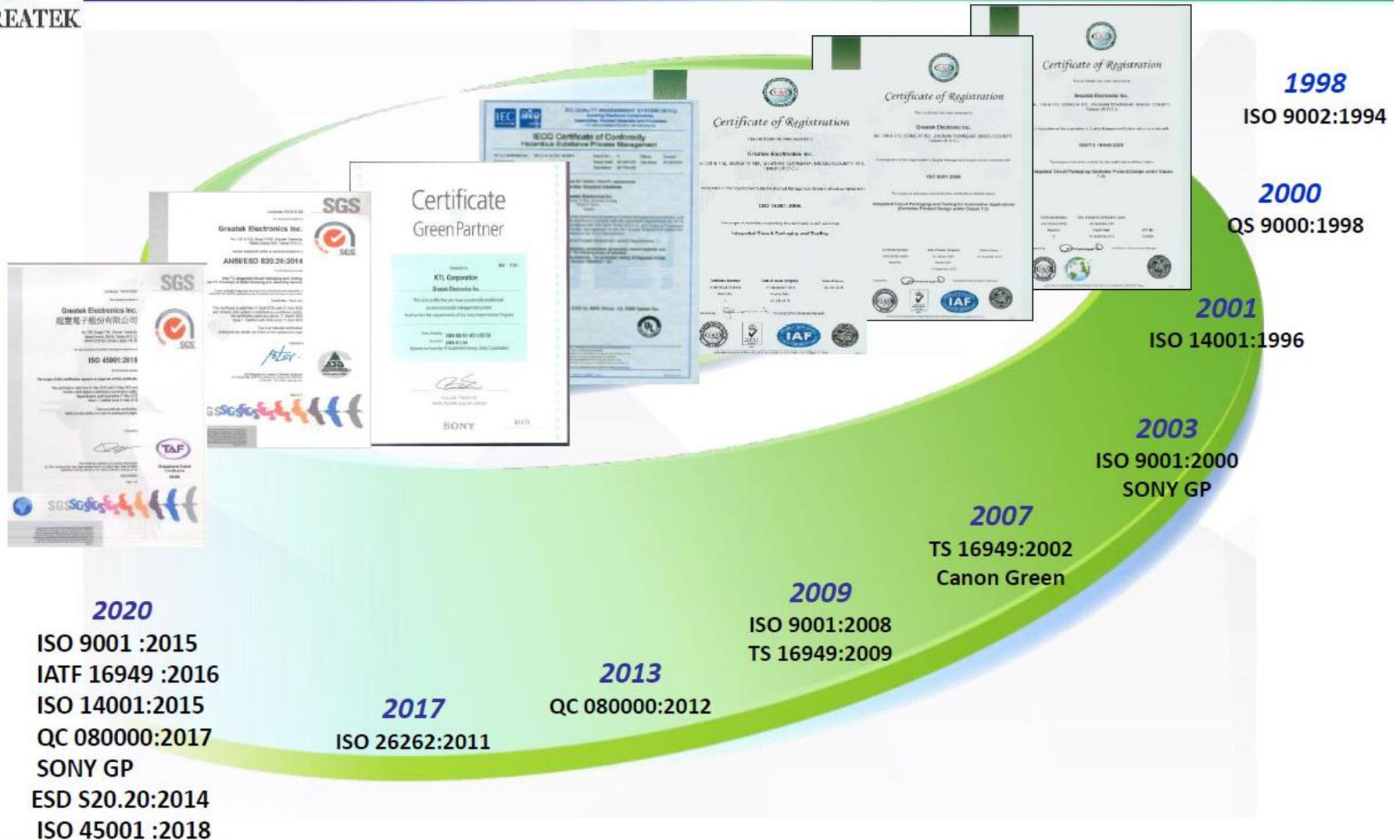
GREATEK CONFIDENTIAL

| | As Is (Gong-Yi, Site 1) | As Is (Gong-Yi, Site 2) | To Be (Toufen, Site 3) |
|---------------------------------|--|-----------------------------|---------------------------|
| 1. GTK Certificate | o | o | o |
| 2. Quality Management System | Management review : CIP review / KPI review / Yield and Cycle Time review Same E-system : SPC / Maintenance / Material / GP / Calibration / OPL | | |
| 3. Clean Room & ESD Control | Same control method | | |
| 4. Training Management System | Use Same Qualification Certificate System | | |
| 5. Production Management System | Same control rule, Recipe and material and tools are all controlled by barcode system. | | |
| 6. 4M Analysis Summary | o | o | o |



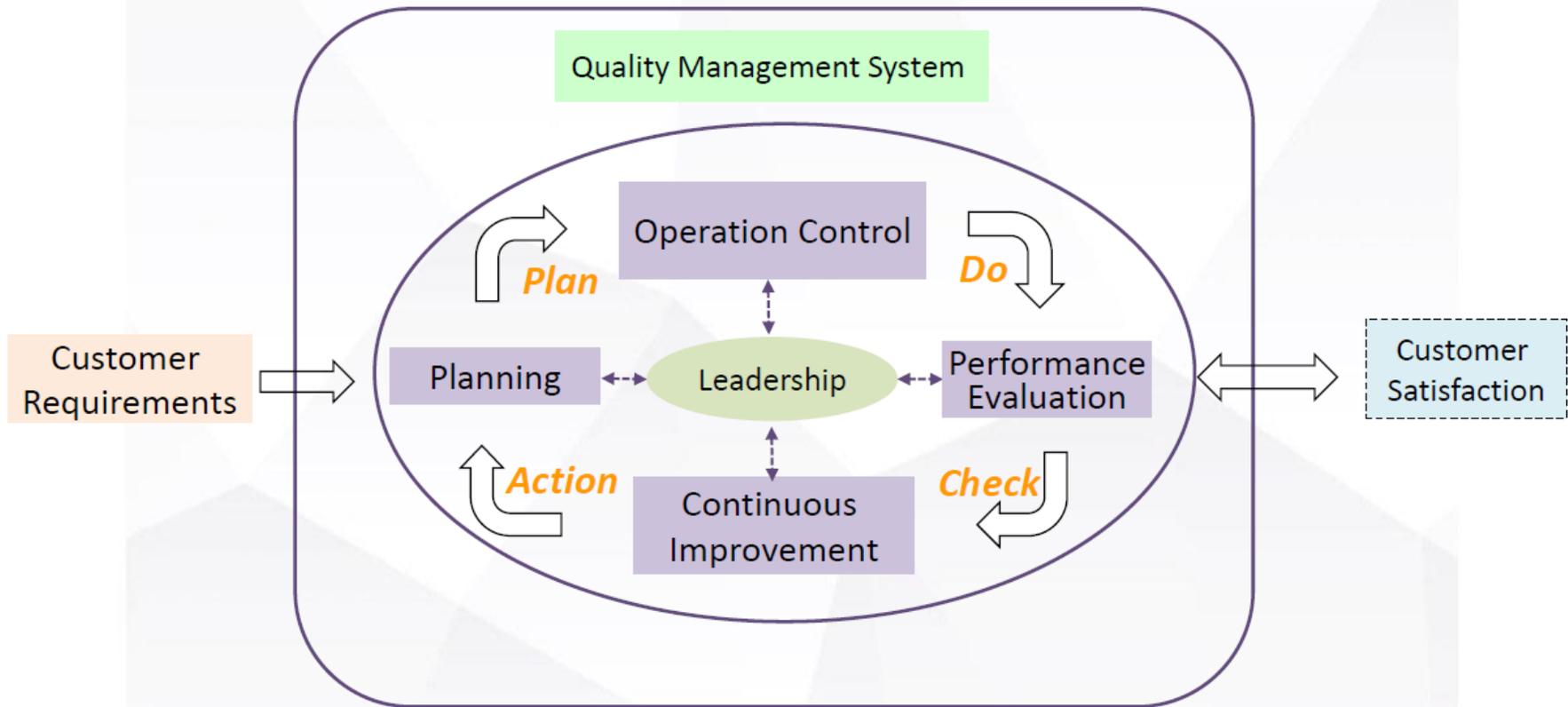
GTK Certificate Milestones

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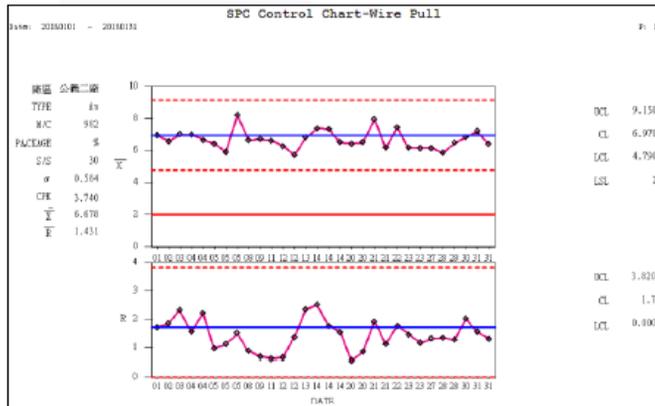
Quality Management System

☐ ISO 9001 / IATF 16949



Management review : Bi-annually
 CIP review : Quarterly
 KPI review : Monthly
 Yield and Cycle Time review : Weekly

1. SPC System



2. Machine Preventive Maintenance System

保養資料處理

機台編號: S-001 周期(月): 12
 保養日期: 20120424 時段: 08:00~12:00 工程師人員: 8137 蕭首孝
 保養人工號: 5096 吳柏鴻 S.O編號: MI-00-211-03-D QA人員: 85053 尹之華

| 項目 | 說明 | 次數 |
|--------|-----------------------|----|
| Y 正常 | (年) 1.旋轉軸油刷長度大於7mm | 10 |
| Y 正常 | (年) 2.之軸潤滑 | |
| Y 正常 | (年) 3.X軸潤滑 | |
| Y 正常 | (年) 4.Y軸潤滑 | |
| Y 正常 | (年) 5.AIR FILTER清潔/更換 | 2 |
| Y 正常 | (年) 6.工作平台平整度14 μm/m | |
| Y 正常 | (年) 7.備案尺寸 | |
| X 暫不停機 | (年) 8.離子風扇探針 | |
| X 暫不停機 | O 9. | |
| X 暫不停機 | O 10. | |
| X 暫不停機 | O 11. | |
| X 暫不停機 | O 12. | |
| X 暫不停機 | O 13. | |
| X 暫不停機 | O 14. | |
| X 暫不停機 | O 15. | |
| X 暫不停機 | O 16. | |
| X 暫不停機 | O 17. | |
| X 暫不停機 | O 18. | |
| X 暫不停機 | O 19. | |
| X 暫不停機 | O 20. | |

3. Calibration Control System

校驗進度查詢

日期: 201206 (YYYYMM) 廠區: H 只需輸入一碼, 公義二廠請輸入H 外校否: N Y/N

| 管理單位 | 儀器名稱 | 校驗編號 | 預校日期 | 實校日期 | 校驗者 | 備註 |
|----------|----------------|-----------|------------|------------|------|-----|
| H520 | 海標尺150MM | H52031043 | 06/11/2011 | 06/04/2011 | Rita | |
| H510 | 冰箱-40°C(N001) | H51051044 | 06/11/2011 | 06/04/2011 | Rita | 新購入 |
| H520(FT) | 測試機(H3TMT67) | H52031471 | 06/11/2011 | 06/04/2011 | Eli | |
| H520(FT) | 測試機(H3TMT92) | H52031475 | 06/11/2011 | 06/04/2011 | Eli | |
| H520(FT) | 測試機(H3TMT69) | H52031473 | 06/11/2011 | 06/04/2011 | Eli | |
| H520(FT) | 測試機(H3TMT54) | H5203944 | 06/11/2011 | 06/04/2011 | Eli | |
| H520(FT) | 測試機(H3TMT55) | H5203945 | 06/11/2011 | 06/04/2011 | Eli | |
| H510 | 冰箱-40°C(N0.02) | H5105683 | 06/11/2011 | 06/04/2011 | Rita | 新購 |
| H520(FT) | 測試機(H3TMT91) | H52031474 | 06/11/2011 | 06/04/2011 | Eli | |
| H520(FT) | 測試機(H3TMT68) | H52031472 | 06/11/2011 | 06/04/2011 | Eli | |

應校驗儀器件數: 142 待校件數: 0 逾期未校件數: 0 達成率: 100.00 %

4. OPL system

OPL - 結果 - Lotus Notes

| 編號 | 名稱 | 類別 | 關聯客戶 | 文件編號/編號 |
|------------------|------------------------------|-----|---------|---------------|
| 3179-SAMSUNG-DOC | | 04 | SAMSUNG | OPL-201310001 |
| HWIC-L20140115 | DIE CRACK DUE TO DIE EJE/CNA | 101 | | OPL-201401001 |
| Q200-20140101 | WRONG BONDING | NA | 103 | OPL-201401002 |
| AALGR14002 | NO AALGR14002 SUBCON.GINA | 102 | | OPL-201401003 |
| AALGR14003 | 成型站作業人員利用氣槍清潔轉N/A | 102 | | OPL-201402001 |
| SAMSUNG-001 | OPL FOR SEMICONDUCTOR :05 | 100 | | OPL-201402002 |
| CIP40225 | OPL -FOR PGL | NA | 104 | OPL-201403001 |
| IBM-001 | SMT REFLOW STRESS FROM NA | 105 | | OPL-201403002 |
| AALGR14004 | NO AALGR14004 SUBCON.GINA | 102 | | OPL-201403003 |
| AALGR14005 | NO AALGR14005 SUBCON.GINA | 102 | | OPL-201403004 |
| AALGR14006 | CP手動貼WAFFER-ID LABEL轉 NA | 102 | | OPL-201403005 |
| CFRGL0201 | PGL X316 DIE CRACK ISSUE | NA | 104 | OPL-201403006 |
| MP1407 | DATE CODE RESTRICTION | NA | 106 | OPL-201403007 |
| WNC-001 | WNC_DIE BOND FILLET HEIG NA | 107 | | OPL-201404001 |

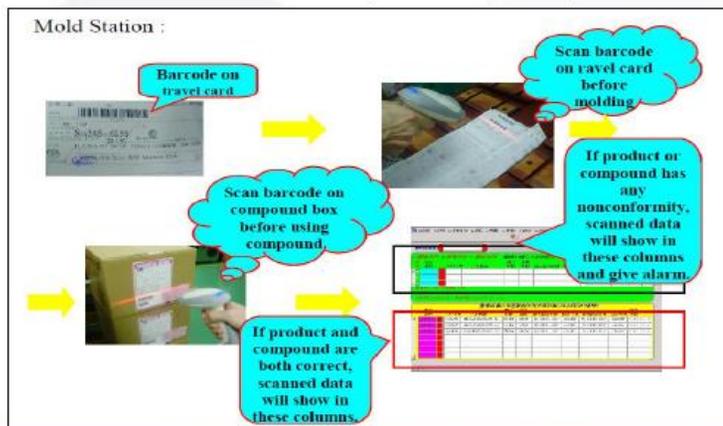
5. Material FIFO Management System



6. GP System (Control ICP & MSDS Report)

| 類別 | 供應商 | 品名 | 噸次 | 到期 | DOCOM別 | MSDS到期 |
|-----|----------------------|--------------|----|------------|--------|-------------|
| ▼原料 | | | | | | |
| | Ablestik(Herkel) | Epoxy | 46 | 2015/07/08 | V0401 | 2015/11/016 |
| | ASM | Lead Frame | 7 | 2015/12/24 | V0115 | 2015/11/025 |
| | Haesung(Samsung MDS) | Lead Frame | 3 | 2015/12/04 | V0111 | 2015/07/10 |
| | HENKEL | 錫膏 | 15 | 2015/09/12 | V0402 | 2016/09/17 |
| | HERAEUS | Du wire | 2 | 2015/07/07 | V0310 | 2016/08/14 |
| | Hitachi | 錫膏 | 2 | 2015/10/13 | V0210 | 2015/11/005 |
| | M.K(Korea) | Bonding wire | 3 | 2015/10/22 | V0305 | 2015/11/05 |
| | NIPPON | Du wire | 2 | 2015/01/05 | V0311 | 2016/09/09 |
| | NITTO | Film | 11 | 2015/08/28 | V0208 | 2016/01/14 |

7. Material Control by Barcode System

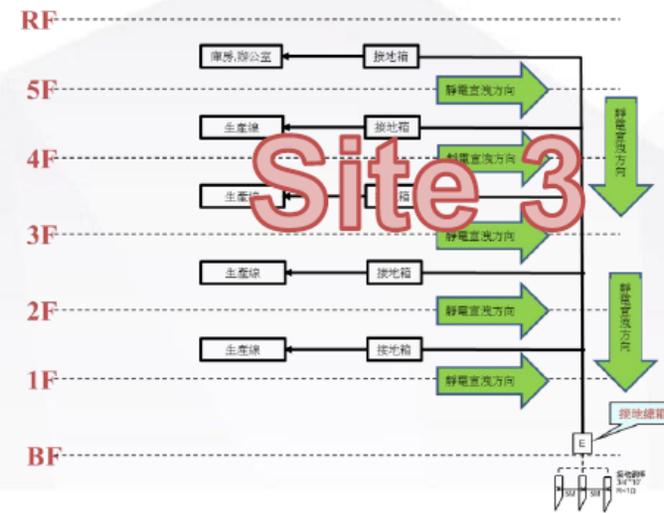
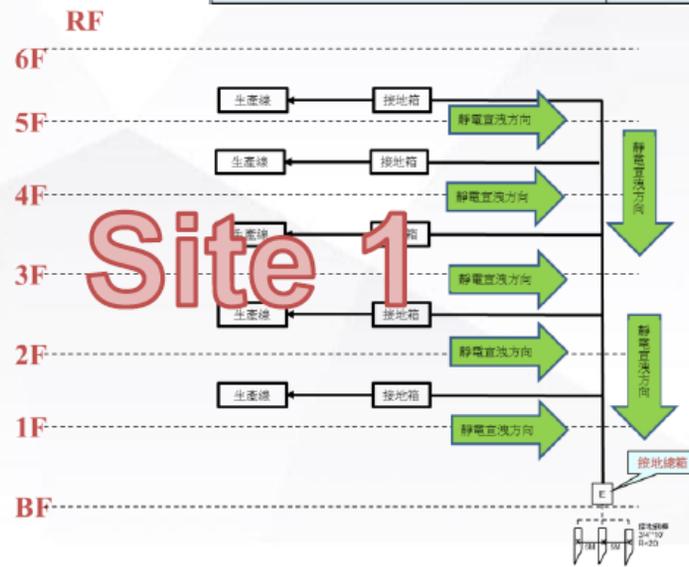




Clean Room & ESD Control--All With Same Criteria

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| Control Item | Criteria | Monitor Frequency | Measurement Instrument |
|---------------------------|---|--------------------|----------------------------|
| Work surface | $1 \times 10^4 \sim 1 \times 10^9 \Omega$ | Quarterly | Height resistivity meter |
| ESD Footwear | $1 \times 10^4 \sim 1 \times 10^9 \Omega$ | Enter Clean Room | Height resistivity meter |
| Wrist Strap | $1 \times 10^4 \sim 1 \times 10^9 \Omega$ | Enter working area | Height resistivity meter |
| Conductive Floor | $1 \times 10^4 \sim 1 \times 10^9 \Omega$ | Quarterly | Height resistivity meter |
| Work Chair | $< 1 \times 10^9 \Omega$ | Quarterly | Height resistivity meter |
| Ion Fan | Decay time | Monthly | Charge Plate Monitor |
| | Balance Voltage | | |
| Product (Material) Shelf | $1 \times 10^4 \sim 1 \times 10^9 \Omega$ | Quarterly | Height resistivity meter |
| Trolley | $1 \times 10^4 \sim 1 \times 10^9 \Omega$ | Quarterly | Height resistivity meter |
| Equipment Grounding | $< 1 \Omega$ | Monthly | Multi-meter |
| Under-floor ESD Network | $< 1 \Omega$ | Annually | Grounded resistivity meter |



ESD criteria meets ANSI S20.20.

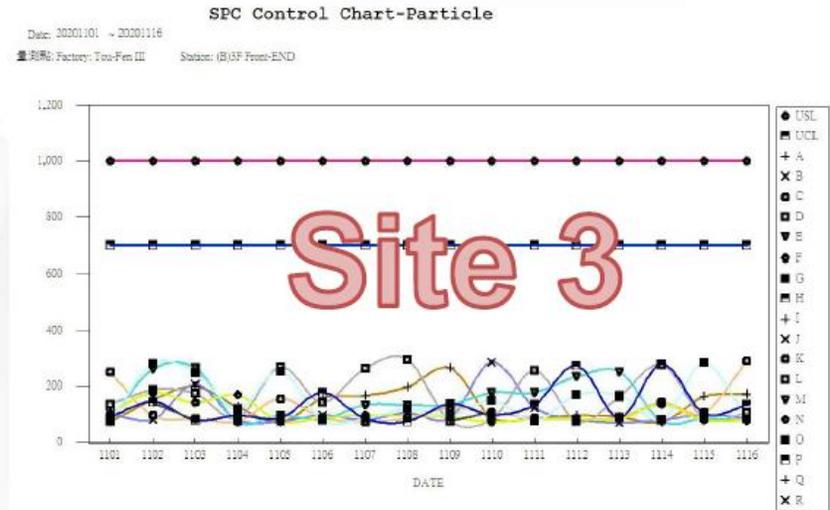


Clean Room & ESD Control

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| Station | Factor | Spec. Limit | Alarm Limit |
|------------|-----------------|-------------|-------------|
| Clean Room | Particle Volume | <1000 *1 | > 700 *1 |

*1:particle q'ty ,size above over 0.5 μm

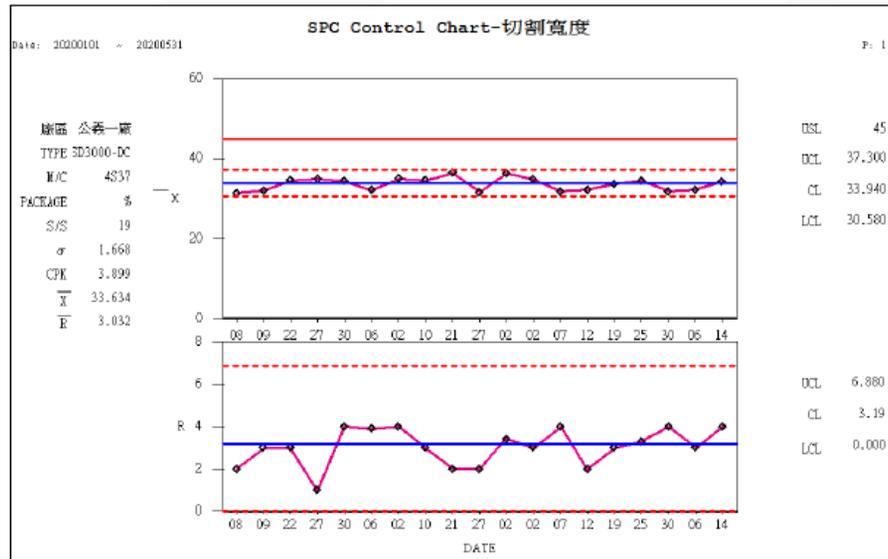




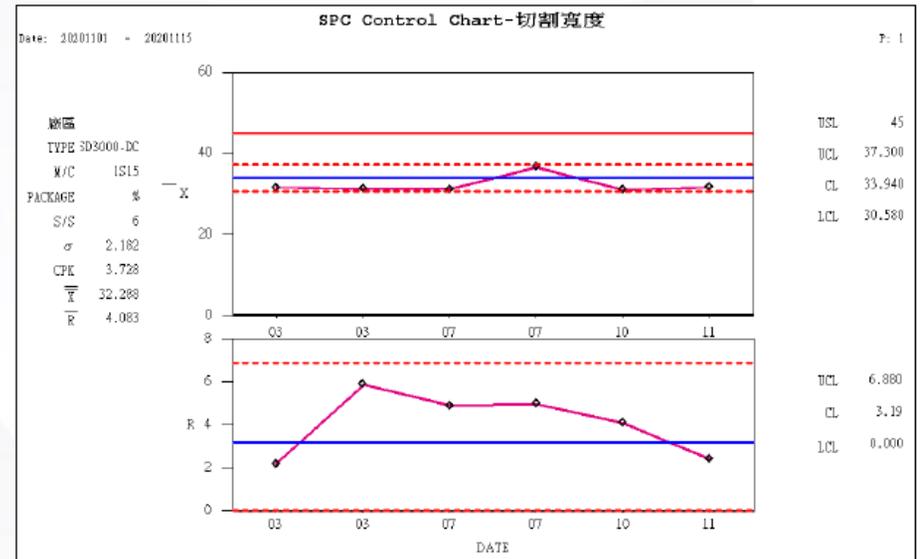
SPC

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Kerf width

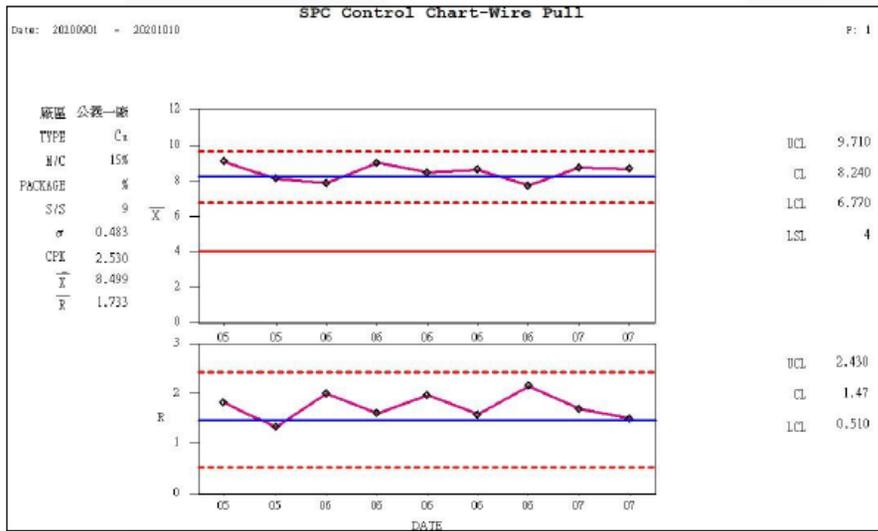


Site 1

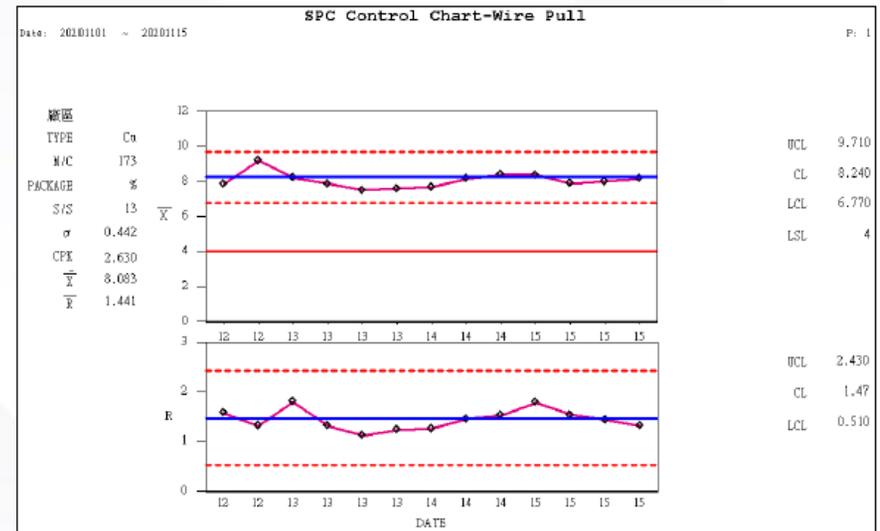


Site 3

Wire pull

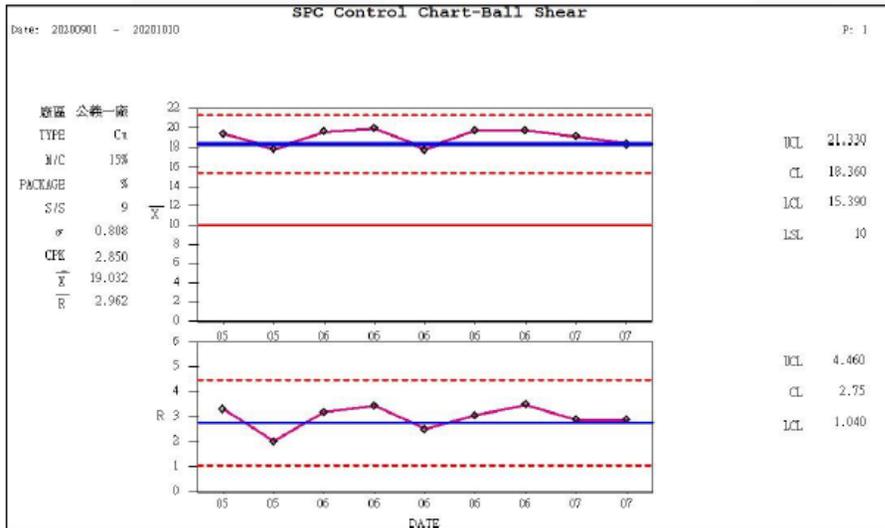


Site 1

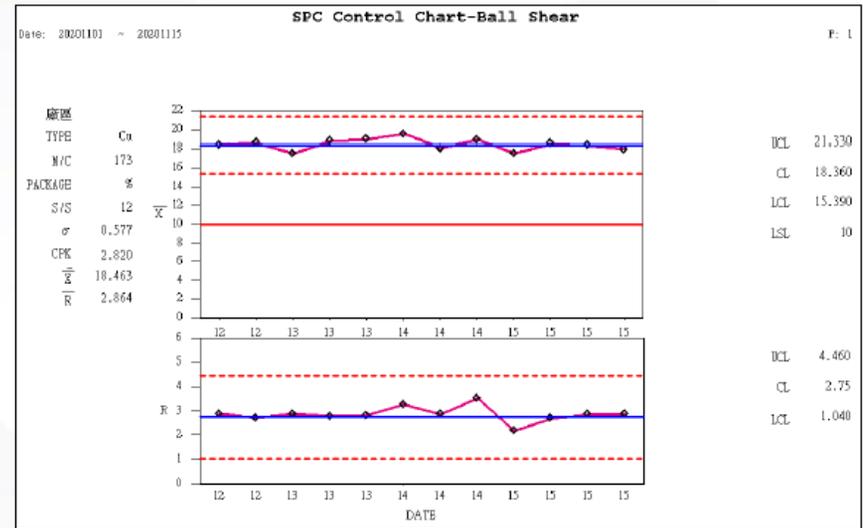


Site 3

Ball shear

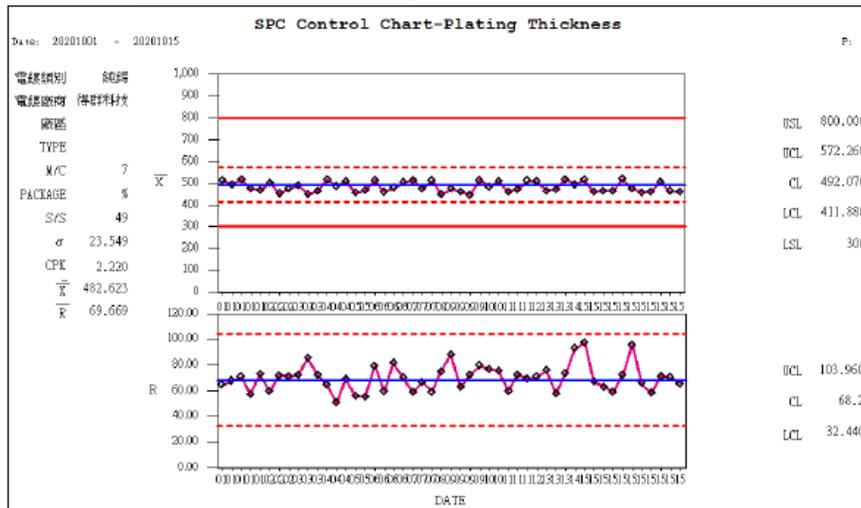


Site 1

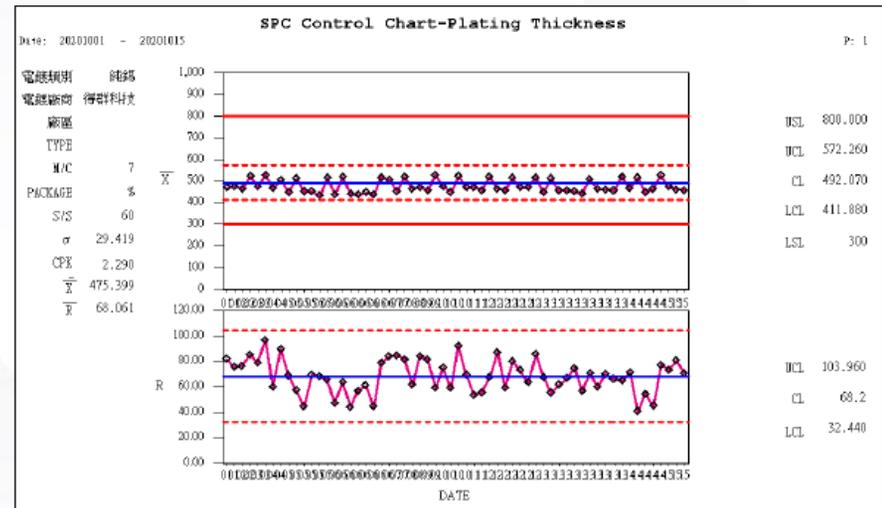


Site 3

Plating thickness



Site 1

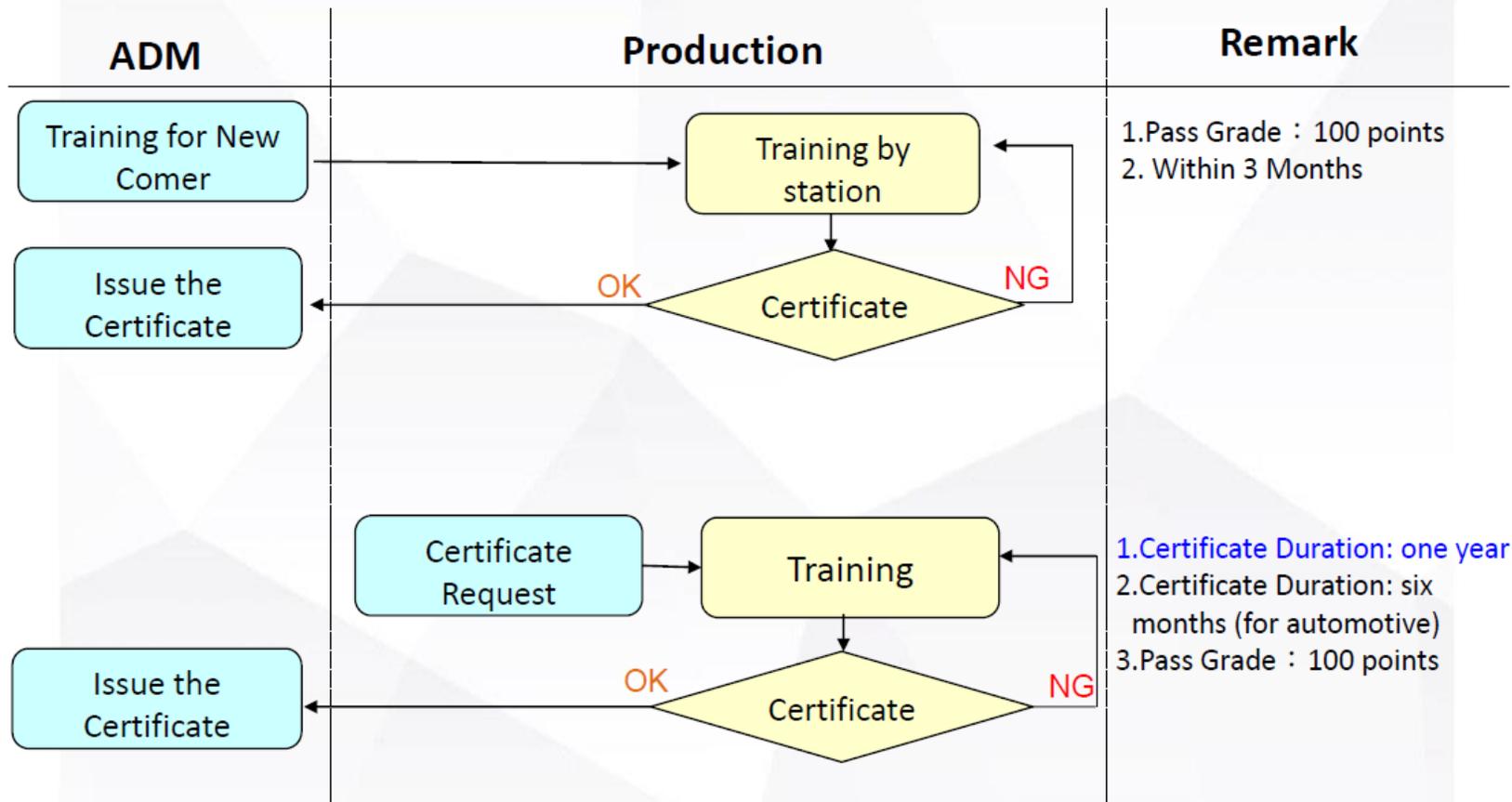


Site 3



Training Management - Certificate Flow

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Qualification Certificate System

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Issue Notice by E-mail



請黃 [redacted] 簽核作業人員認證 [redacted]

showtan 收件者: [redacted]

此訊息附有數位簽章。

請點選此處，以連結申請單，謝謝。

Recording on system

一般作業人員認證

登錄帳號: ga/Greatek

評鑑日: 2017/07/28

| | | | |
|----|-----------|----|--|
| 部門 | H530製一部二廠 | 班別 | C A(E,G,常日班),B(F,H班) C(I,K班),D(J,L班) |
|----|-----------|----|--|

認證人員:

| 通過 | 工號 | 姓名 | 職稱 | 班別 | 站別碼 | 說明 | 上次認證日/ 吊銷日 | 筆試 成績 | 實作 成績 | 認證 類別 |
|----|--------|-----|----|----|-------|--------|---------------|----------|----------|----------|
| 通過 | 85034 | 賴碧貞 | 領 | C | 230-1 | ESEC機台 | 2016/08/05 | 100 | 100 | 重 |
| 通過 | 950479 | 風春梅 | 技 | C | 230-3 | 三目視 | 2016/08/05 | 100 | 100 | 重 |
| 通過 | 950572 | 李憶華 | 技 | C | 230-1 | ESEC機台 | 2016/08/05 | 100 | 100 | 重 |

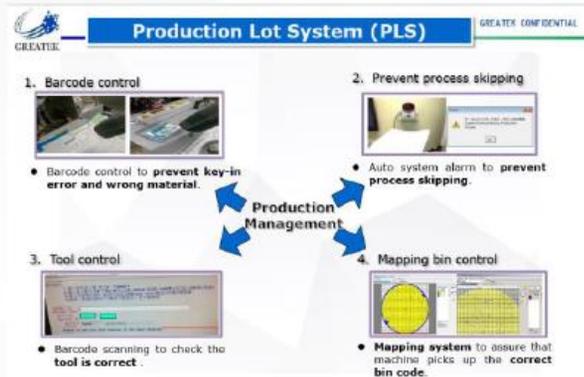
To issue the Qualified Work Badge



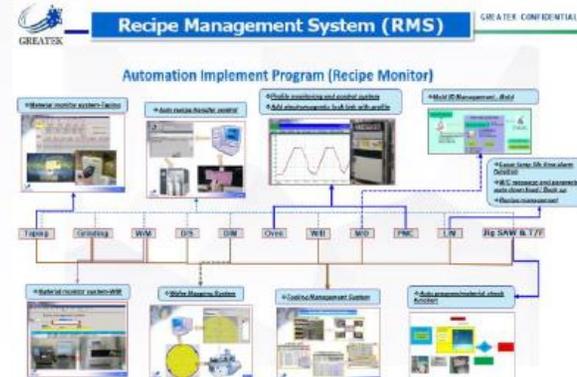
No allow production if no certification (by system control)

Production Management System

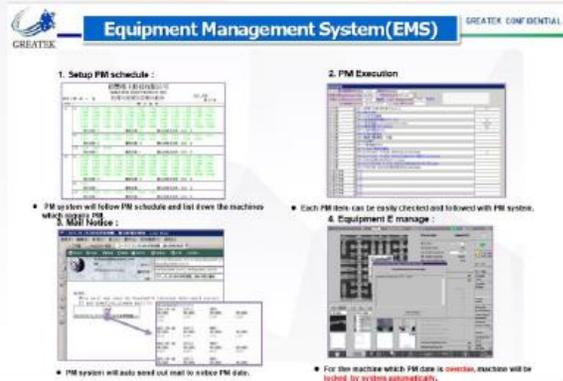
1. Production Lot System



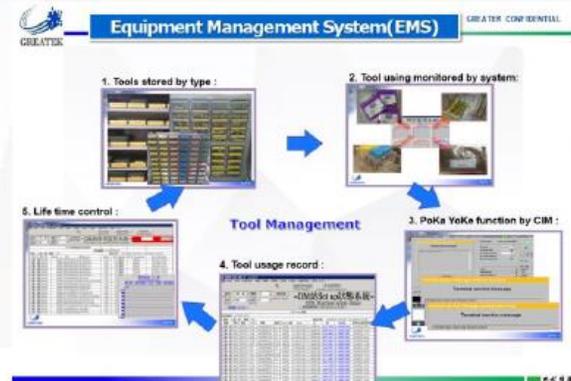
2. Recipe Management System



3. Equipment Management System



4. Tool & Material Management System



4M Analysis (QFN for P1 & P3)

Front End

Back End

| Process Name | | Gung-Yi Plant I | Toufen Plant |
|----------------|----------|--|--|
| Wafer IQC | Man | Qualification by Spec. QI-00-001 | Qualification by Spec. QI-00-001 |
| | Machine | High Power Microscope | High Power Microscope |
| | Material | - | - |
| | Method | Follow Spec. QI-00-001 | Follow Spec. QI-00-001 |
| Wafer Grinding | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | 8540 / 8560 / 8761 | 8560 / 8761 |
| | Material | - | - |
| | Method | Follow Spec. OI-00-190 | Follow Spec. OI-00-190 |
| Laser Grooving | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | DFL7161 | DFL7161 |
| | Material | Diso Hogomax003 | Diso Hogomax003 |
| | Method | Follow Spec. OI-00-240 | Follow Spec. OI-00-240 |
| Wafer Saw | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | DFD6361 / DFD6560 | DFD6560 |
| | Material | - | - |
| | Method | Follow Spec. OI-00-210 | Follow Spec. OI-00-210 |
| Die Mounting | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | Besi 2100 | Besi 2100 |
| | Material | Follow BOM (Lead Frame / Epoxy / Film) | Follow BOM (Lead Frame / Epoxy / Film) |
| | Method | Follow Spec. OI-00-220 | Follow Spec. OI-00-220 |
| Wire Bond | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | KNS Procu-LA | KNS Procu-LA |
| | Material | Follow BOM (Cap / Wire) | Follow BOM (Cap / Wire) |
| | Method | Follow Spec. OI-00-230 | Follow Spec. OI-00-230 |

| Process Name | | Gung-Yi Plant I | Toufen Plant |
|----------------|----------|---|----------------------------------|
| Molding | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | TOWA | TOWA |
| | Material | Compound | Compound |
| | Method | Follow Spec. OI-00-310 | Follow Spec. OI-00-310 |
| Marking | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | EO-SY2002 | EO-SY2002 |
| | Material | - | - |
| | Method | Follow Spec. OI-00-325 | Follow Spec. OI-00-325 |
| Singulation | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | FMS3040 | FMS3040 |
| | Material | Leadframe | Leadframe |
| | Method | Follow OI-00-537 | Follow OI-00-537 |
| T/R L/S | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | Micro Vision 996M series ISMECA series | ICOS T740 ISMECA series |
| | Material | - | - |
| | Method | Follow OI-00-726 | Follow OI-00-726 |
| Packing (tray) | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | JF-325 | JF-325 |
| | Material | - | - |
| | Method | Follow OI-00-720 | Follow OI-00-720 |

4M Analysis (L/F Base for P1 & P2)

Front End

| Process Name | | Gung-Yi Plant I | Gung-Yi Plant II |
|----------------|----------|---|--|
| Wafer IQC | Man | Qualification by Spec. QH00-001 | Qualification by Spec. QH00-001 |
| | Machine | High Power Microscope | High Power Microscope |
| | Material | - | - |
| | Method | Follow Spec. QH00-001 | Follow Spec. QH00-001 |
| Wafer Grinding | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | 850 / 8540 / 8560 / 8761 | 841 / 850 / 8560 |
| | Material | - | - |
| | Method | Follow Spec. OH00-190 | Follow Spec. OH00-190 |
| Laser Grooving | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | DFL7161 | DFL7161 |
| | Material | Diso Hogomax003 | Diso Hogomax003 |
| | Method | Follow Spec. OH00-240 | Follow Spec. OH00-240 |
| Wafer Saw | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | DFD641 / DFD651 / DFD6340 / DFD6361 / DFD6560 | DFD640 / DFD641 / DFD651 / DFD6361 / DFD6560 |
| | Material | - | - |
| | Method | Follow Spec. OH00-210 | Follow Spec. OH00-210 |
| Die Mounting | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | Best 2007 / 2008 / 2100 | Best 2007 / 2008 / 2100 |
| | Material | Follow BOM (Lead Frame / Epoxy / Film) | Follow BOM (Lead Frame / Epoxy / Film) |
| | Method | Follow Spec. OH00-220 | Follow Spec. OH00-220 |
| Wire Bond | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | ESEC 3100 / 3200 KNS Probu / ProCu-LA | ESEC 3100 / 3200 KNS Probu |
| | Material | Follow BOM (Cap / Wire) | Follow BOM (Cap / Wire) |
| | Method | Follow Spec. OH00-230 | Follow Spec. OH00-230 |

Back End

| | | Gung-Yi Plant I | Gung-Yi Plant II |
|-------------------|----------|----------------------------------|----------------------------------|
| Molding | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | TOWA Y series | TOWA Y series |
| | Material | Compound | Compound |
| | Method | Follow Spec. OH00-310 | Follow Spec. OH00-310 |
| Marking | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | EO-SY2002 | EO-SY2002 |
| | Material | - | - |
| | Method | Follow Spec. OH00-325 | Follow Spec. OH00-325 |
| T/F | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | GMM CP150 / SU51 | GMM CP150 / SU51 |
| | Material | Leadframe | Leadframe |
| | Method | Follow OH00-520 | Follow OH00-520 |
| T/R L/S | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | Microvision 996 series | Microvision 996 series |
| | Material | - | - |
| | Method | Follow OH00-726 | Follow OH00-726 |
| Packing (tray) | Man | Qualification by Spec. AD-00-104 | Qualification by Spec. AD-00-104 |
| | Machine | JF-325 | JF-325 |
| | Material | - | - |
| | Method | Follow OH00-720 | Follow OH00-720 |

Appendix B: Greatek reliability test report



GREATEK ELECTRONICS INC.

No.136, Gong-Yi Rd., Zhunan Township, Miaoli County 350, Taiwan R.O.C.

Tel : (037)638-568 Fax : (037)628-323

Reliability Test Report

Customer : Greatek

Purpose : Reliability Test.

Package Type : QFN 32L (5x5x0.75mm)

Report No : Q710-RELI-C19082025

Report Date : 23-SEP-2019

Conclusion : The test results were all passed.

Approved By :

Handwritten signature of J.P. Huang in black ink.

Date : 23-SEP-2019

Prepared By :

Handwritten signature of Cloud in black ink.

Date : 23-SEP-2019

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1. Sample Background

1.1 Sample Background:

| | | | |
|----------------|-----------------------------|----------------|----------------------------|
| Package Type : | QFN 32L (5x5x0.75mm) | L/F Material : | C7025 |
| Device : | CS*** | Lead Frame: | 134*134 mil |
| Lot No: | PG9A121B6 | Epoxy: | 1076DJ-G |
| Mo No: | *** | Wire: | Cu wire 0.8mil |
| Date code : | *** | Compound | G700H |
| Exposed pad : | NO | Lead Finish | Pure Tin |
| Apply Date: | 09-AUG-2019 | Sample Size: | 135EA |
| Complete Date: | 20-SEP-2019 | Report No: | Q710-RELI-C19082025 |



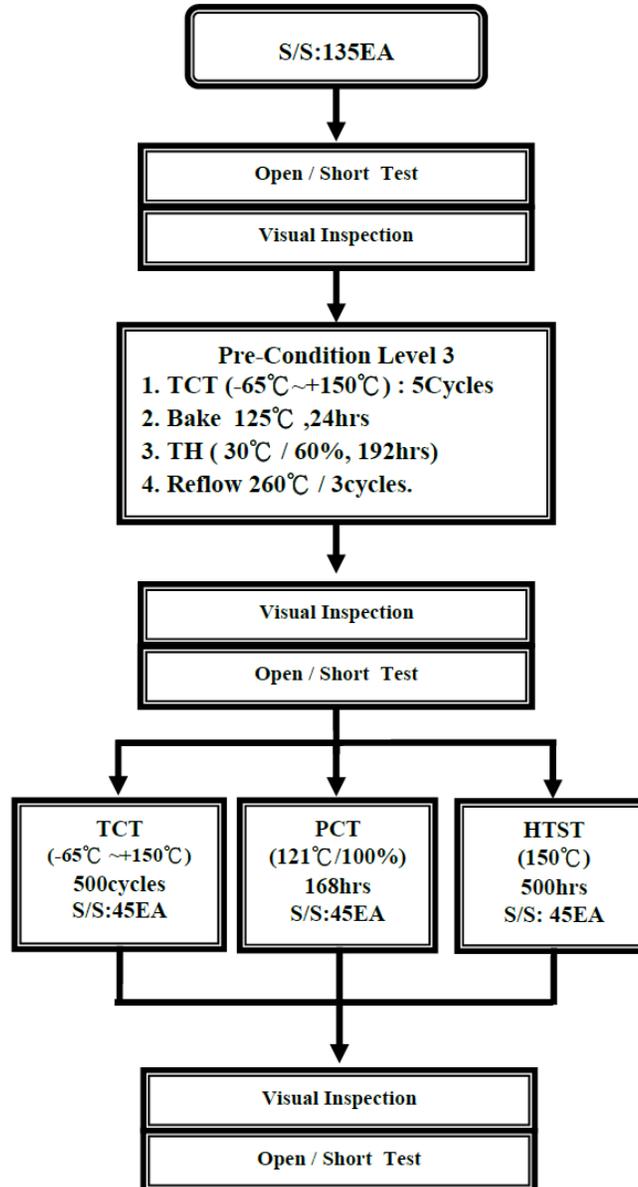
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2. Test Flow Chart

2.1 Precondition:





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3. Inspection method

3.1 Visual Inspection:

Purpose: In order to check whether the samples have package crack or not before/after reliability test.

Apparatus: Power Scope (7~40x)

3.2 SAT Inspection:

Purpose: Inspecting the delamination of concerned layer.

Apparatus: SONIX ECHO-VS

4. Environment Stress / Mechanical Test

4.1 Precondition:

This test method establishes an industry standard preconditioning flow for plastic SMDs (surface mount device) that is representative of a typical industry multiple solder reflow operation.

Test procedure is as following:

Stept1: TCT (-65°C~+150°C) : 5Cycles

Stept2: Bake 125°C ,24hrs

Stept3: Moisture Soak (30°C / 60% / 192hrs)

Stept4: Reflow 260°C / 3cycles

4.2 Pressure Cooker Test :

The "Accelerated Moisture Resistance Test" is performed for the purpose of evaluating the moisture resistance of nonhermetic packaged solid state devices. It employs severe conditions of pressure, humidity and temperature that accelerate the penetration of moisture through the external protective material (encapsulant or seal) or along the interface between the external protective material and the metallic conductors that pass through it. This test is destructive; it may* be used for qualification, lot acceptance and as a product monitor.

Test condition: 121°C/100%, 2atm, 168hrs.

4.3 Temperature Cycle Test :

This test is conducted to determine the resistance of a part to extremes of high- and low-temperatures, and to the effect of alternate exposures to these extremes.

Test condition: -65°C ~ +150°C, 500cycles.

4.4 High Temperature Storage Life:

The purpose of this test is to determine the effect on solid state electronic devices of storage at elevated temperature without electrical stress applied. This test is considered destructive and, therefore, is applicable for device qualification.

Test condition: 150°C, 500hrs



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5. Reliability Test Results

5.1 Summary of test results :

| Test Procedure | Sample Size | Visual Insp. Rej/s.s | Open / Short Test rej/s.s | SAT insp Rej/s.s | Judgment |
|-----------------------------|-------------|----------------------|---------------------------|------------------|----------|
| Before Pre-condition | 135EA | 0/135 | 0/135 | 0/45 | PASS |
| After Pre-condition | 135EA | 0/135 | 0/135 | 0/45 | PASS |
| PCT 168hrs | 45EA | 0/45 | 0/45 | N/A | PASS |
| TCT 500cycles | 45EA | 0/45 | 0/45 | N/A | PASS |
| HTST 500hrs | 45EA | 0/45 | 0/45 | N/A | PASS |



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5.2 Detail Informations of SAT Inspection :

5.2-1 Before Precondition :

| Focus | Die Surface | | Lead Surface (Top side) | | | Die Pad (Top side) | |
|-------|-------------|---------|-------------------------|----------------------------|---------------------------|--------------------|---------|
| | 0% acc | >0% rej | 0% acc | Partial length on lead acc | Entire length on lead rej | 0% acc | >0% rej |
| S/S | 45 | 0 | 45 | 0 | 0 | 45 | 0 |

5.2-2 After Precondition :

| Focus | Die Surface | | Lead Surface (Top side) | | | Die Pad (Top side) | |
|-------|-------------|---------|-------------------------|----------------------------|---------------------------|--------------------|---------|
| | 0% acc | >0% rej | 0% acc | Partial length on lead acc | Entire length on lead rej | 0% acc | >0% rej |
| S/S | 45 | 0 | 45 | 0 | 0 | 45 | 0 |



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6. Conclusion

The test results were all passed.

7. Reference

- * **JESD22-A113** Preconditioning of Plastic Surface Mount Devices Prior to Reliability Testing
- * **IPC/JEDEC J-STD-020E** Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices.
- * **JESD22-A101** Temperature/Humidity Chamber Operation Instruction
- * **JESD22-A102** Pressure Cooker Test
- * **JESD22-A103** High Temperature Storage Life Test
- * **JESD22-A104** Temperature cycling
- * **Greatek Spec #QA-00-402** SAT Operation Instruction



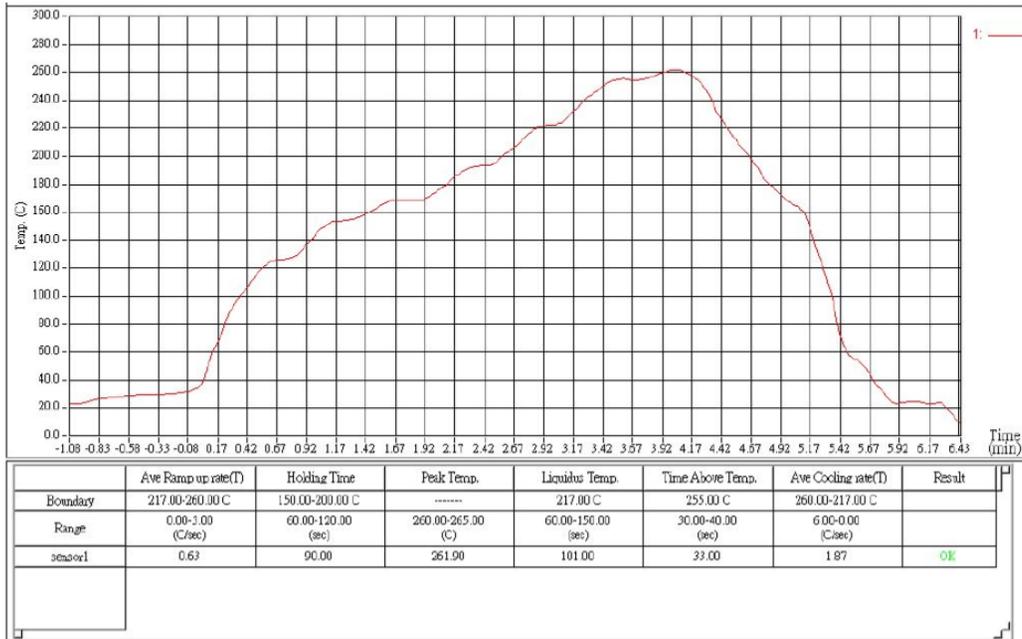
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8. Attachments:

PROFILE for SMD.



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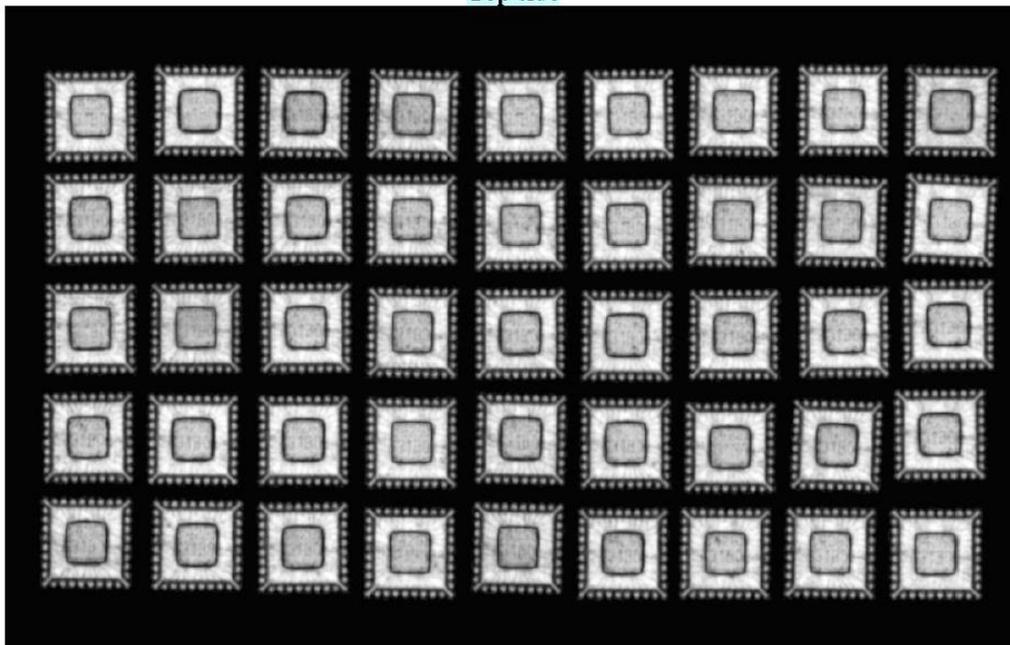
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9. SAT Photo :

Before Precondition :

Top side



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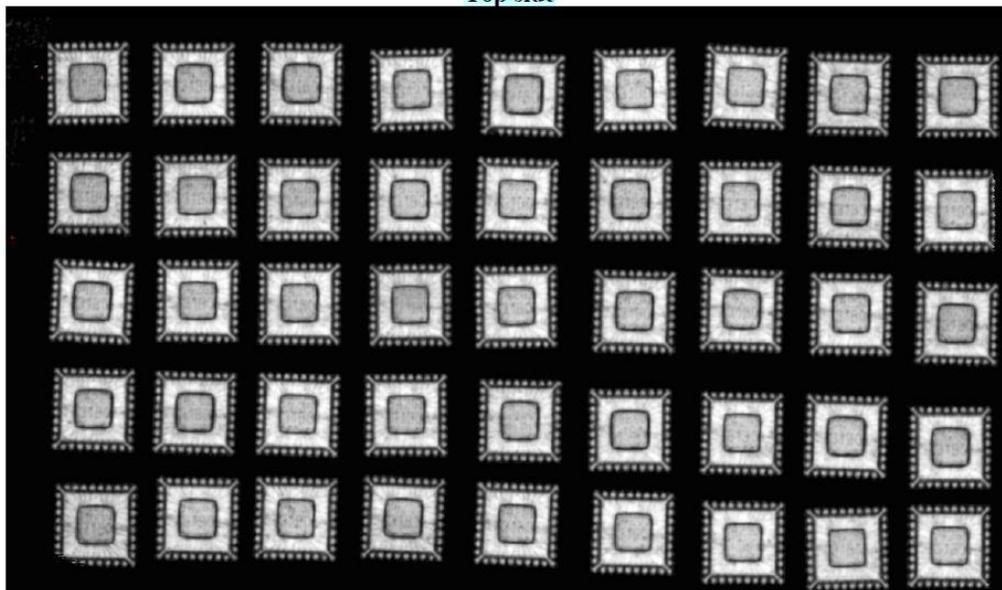
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After Precondition :

Top side



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